Description

The XPX2080FD uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

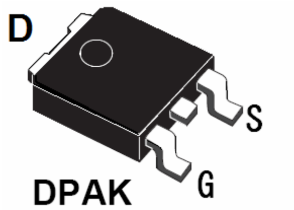
V_{DS} =20V, I_D =85A

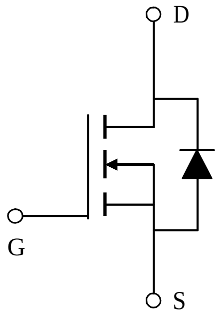
$R_{DS(ON)}$=2.8mΩ (typ) @ V_{GS}=4.5V

$R_{DS(ON)}$=4mΩ (typ) @ V_{GS}=2.5V

General Features

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation





Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2080	XPX2080FD	TO-252-2L	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Symbol	Parameter	Max.	Units
VDSS	Drain-Source Voltage	20	V
VGSS	Gate-Source Voltage	±12	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	85	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1]	62	A
IDM	Pulsed Drain Current note1	380	A
EAS	Single Pulsed Avalanche Energy note2	110	mJ
P_D	Power Dissipation	83	W
RθJC	Thermal Resistance, Junction to Case	1.95	℃/W
TJ, TSTG	Operating and Storage Temperature Range	-55 to +150	℃

Electrical Characteristics (T_C=25℃unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250μA	20	22	-	V
IDSS	Zero Gate Voltage Drain Current	V_{DS}=20V, V_{GS}=0V	-	-	1	μA
IGSS	Gate to Body Leakage Current	V_{GS}= ±12V, V_{DS}=0V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250μA	0.5	0.68	1.0	V
RDS(on)	Static Drain-Source On-Resistance note3	V_{GS}=4.5V, I_D=30A	-	2.8	3.5	mΩ
		V_{GS}=2.5V, I_D=20A		4	6	
C_{iss}	Input Capacitance	V_{DS}=10V, V_{GS}=0V, f=1.0MHz	-	3200	-	pF
Coss	Output Capacitance		-	460	-	pF
Crss	Reverse Transfer Capacitance		-	445	-	pF
Q_g	Total Gate Charge	V_{DS}=10V, I_D=30A, V_{GS}=4.5V	-	48	-	nC
Q_{gs}	Gate-Source Charge		-	3.6	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	19	-	nC
td(on)	Turn-On Delay Time	V_{DS} =10V, I_D=30A, R_G=1.8Ω, V_{GS}=4.5V	-	9.7	-	ns
t_r	Turn-On Rise Time		-	37	-	ns
td(off)	Turn-Off Delay Time		-	63	-	ns
t_f	Turn-Off Fall Time		-	52	-	ns
IS	Maximum Continuous Drain to Source Diode Forward Current		-	-	90	A
ISM	Maximum Pulsed Drain to Source Diode Forward Current		-	-	360	A
VSD	Drain to Source Diode Forward Voltage	V_{GS}=0V, I_{SD}=30A, T_J=25℃	-	-	1.2	V
t_{rr}	Reverse Recovery Time	T_J=25°C, I_F=30A, di/dt =100A/μs	-	23	-	ns
Q_{rr}	Reverse Recovery Charge		-	10	-	nC

Note :

1、The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.
2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
3、The EAS condition: T_J=25℃, V_{DD}=15V, V_G=4.5V, R_G=25Ω, L=0.5mH, I_{AS}=21A
4、The power dissipation is limited by 175℃ junction temperature
5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

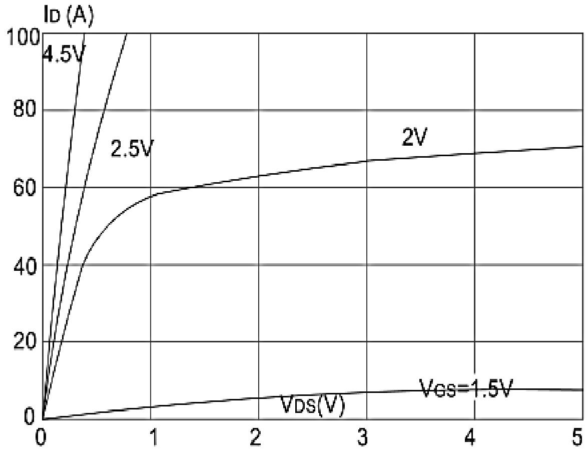


Figure1: Output Characteristics

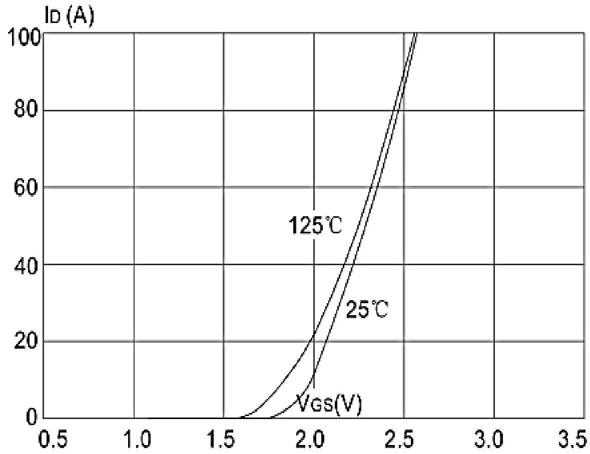


Figure 2: Typical Transfer Characteristics

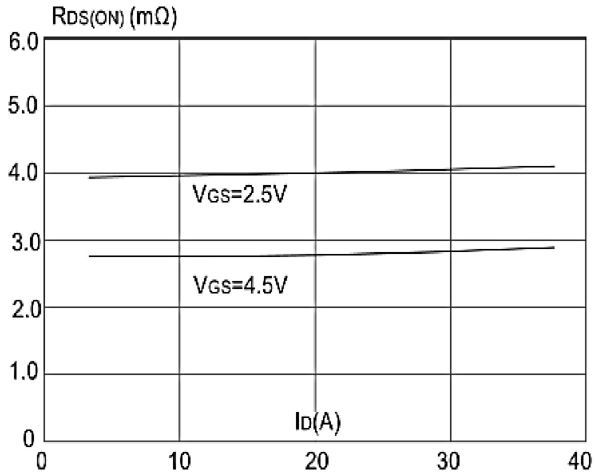


Figure 3:On-resistance vs. Drain Current

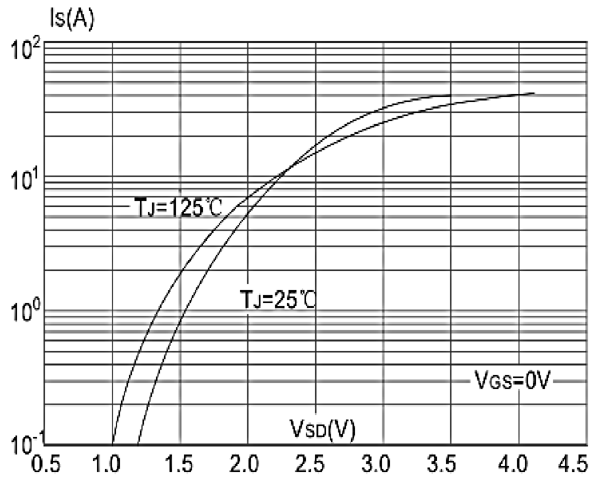


Figure 4: Body Diode Characteristics

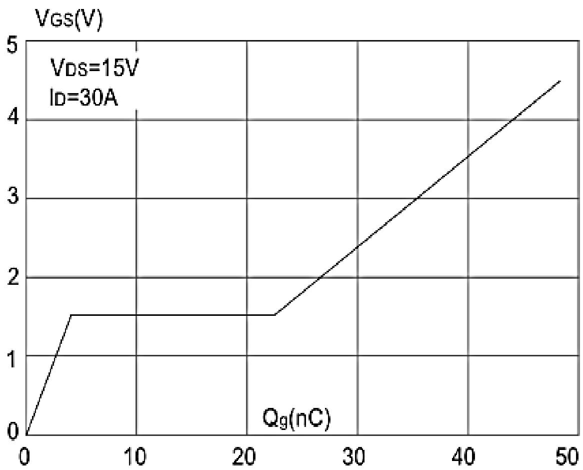


Figure 5: Gate Charge Characteristics

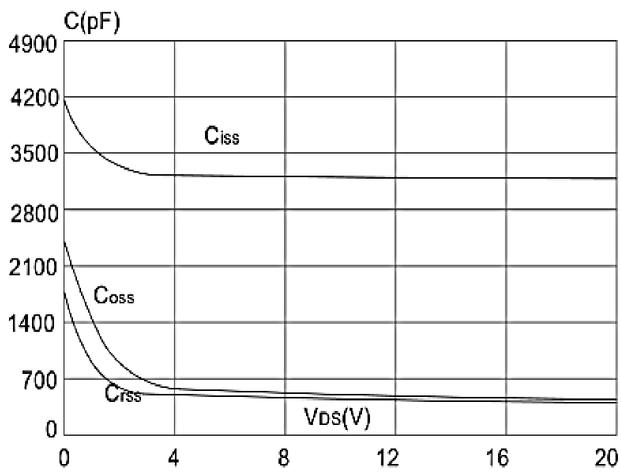


Figure 6: Capacitance Characteristics

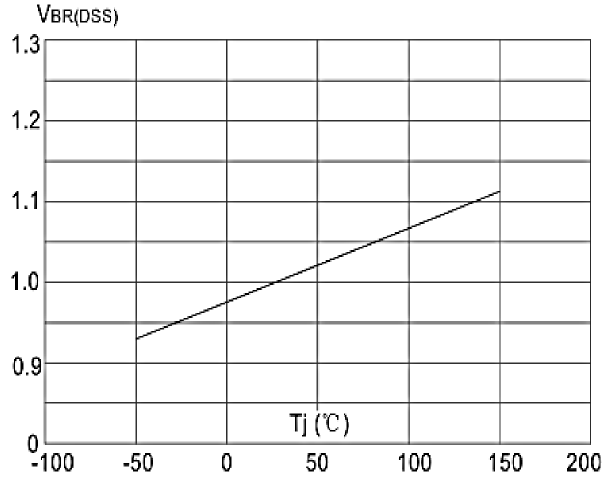


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

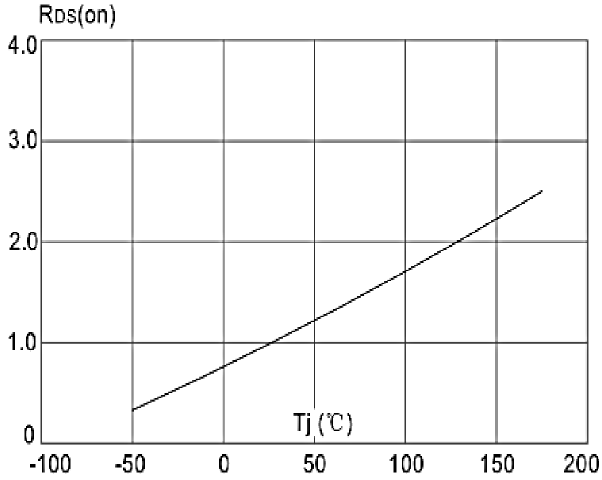


Figure 8: Normalized on Resistance vs. Junction Temperature

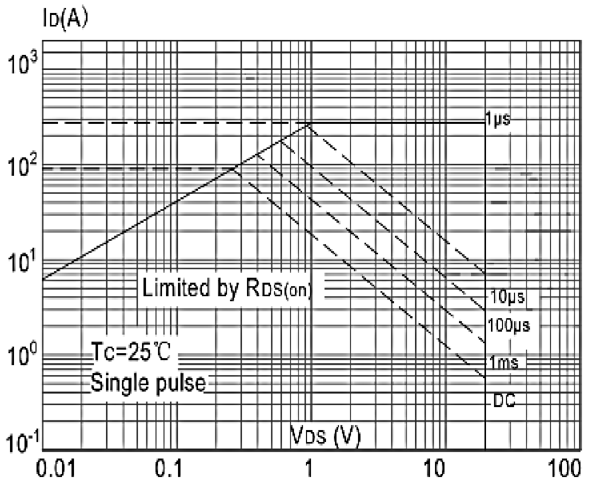


Figure 9: Maximum Safe Operating Area

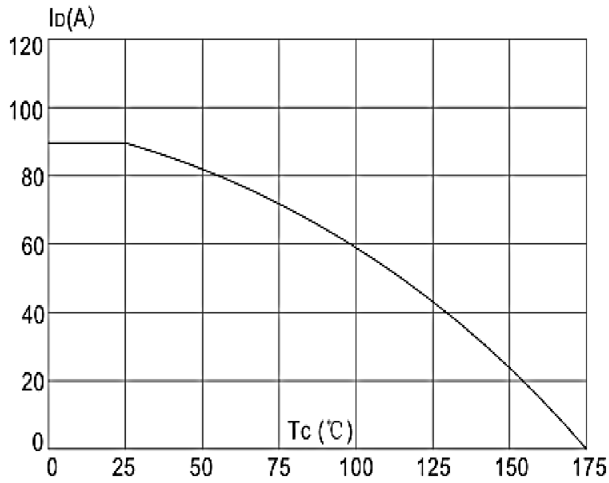


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

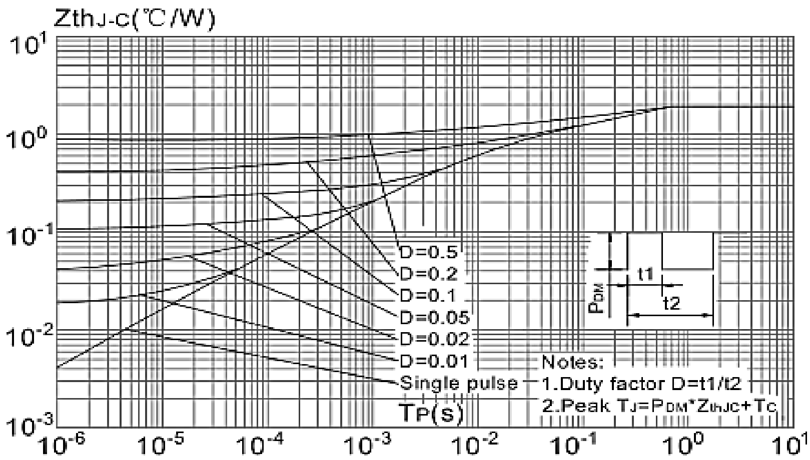
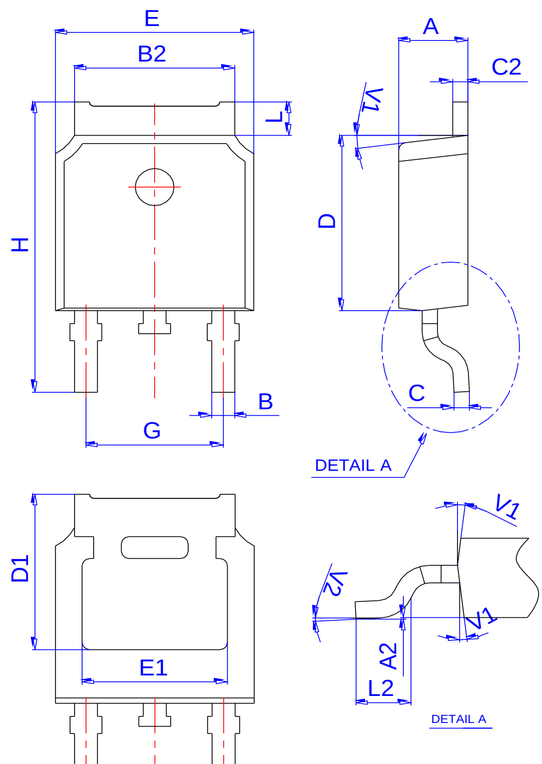


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambien

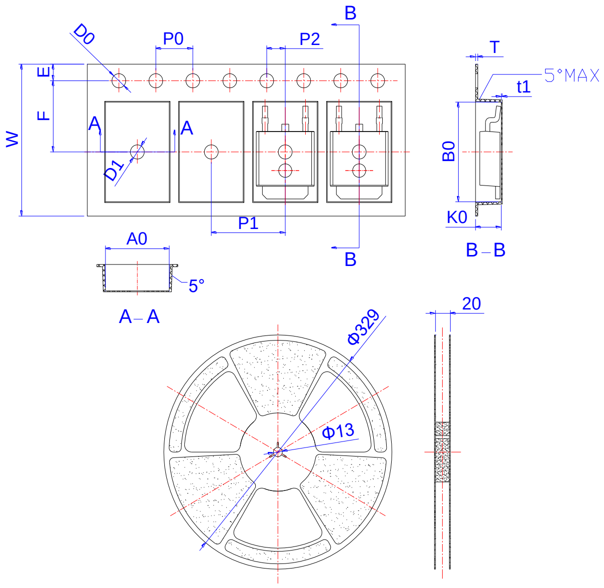
Package Mechanical Data:TO-252-3L



TO-252

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1		5.30REF			0.209REF	
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

Flow (wave) soldering (solder dipping)

Product	Peak Temperature	Dipping Time
Pb device	245℃±5℃	5sec±1sec
Pb-Free device	260℃+0/-5℃	5sec±1sec

This integrated circuit can be damaged by ESD UniverChip Corporation recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedure can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

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